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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re the Application of: Tsuga et al.

Docket No.: TI-31619

Serial No.: 10/072,073

Art Unit: 1746

Filed: 02/08/02

Examiner: Kornakov, M.

Title: Method for Removing Particles on Semiconductor Wafers

**AMENDMENT UNDER 37 CFR §1.312**

November 7, 2005

Mail Stop Issue Fee  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)**

I hereby certify that the above correspondence is being deposited with the U.S. Postal Service on 11-7-05 as First Class Mail in an envelope addressed to: Mail Stop Issue Fee, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Karen Vertz  
Karen Vertz

11-7-05  
Date

This application is in condition for allowance except for the correction of formal matters. In response to the Notice of Drawing Inconsistency with Specification, dated 10/24/2005, in the above-identified patent application, please make the following amendments. They are respectfully submitted as a full and complete response to the Notice. Charge any required fees to the deposit account of Texas Instruments Incorporated, Account No. 20-0668.